

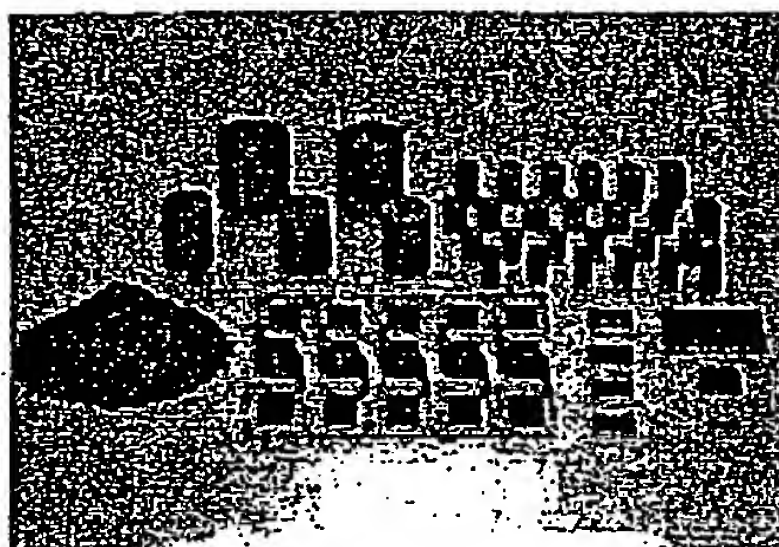
Appl. No. 09/874,666
Amdt. Dated 10/04/2004
Reply to Office Action of 07/06/2004

Appendix A

Appl. No. 09/874,666
 Amdt. Dated 10/04/2004
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A-1

Semiconductor Materials 6 6



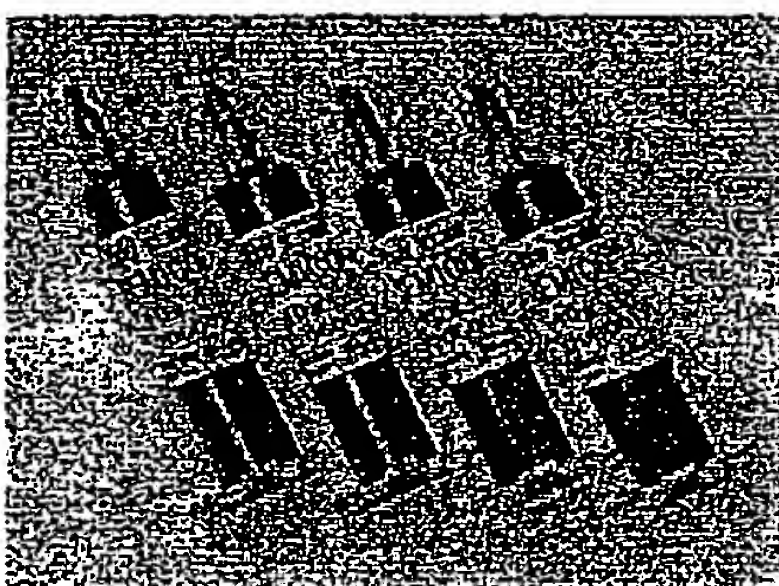
Epoxy molding compounds

For inquiry 6

These encapsulating materials provide low stress, low alpha-ray property and high thermal conductivity. They are also environment-friendly.

- Features**
- Superior moisture resistance, electrical characteristics, and moldability. This material meets the high requirements for resin encapsulation of devices.
 - By introducing a new, original flame-retardant system, this product is free from halogen and antimony trioxide.

Applications ● D-RAM and other LSI molding, full pack molding for power devices etc.

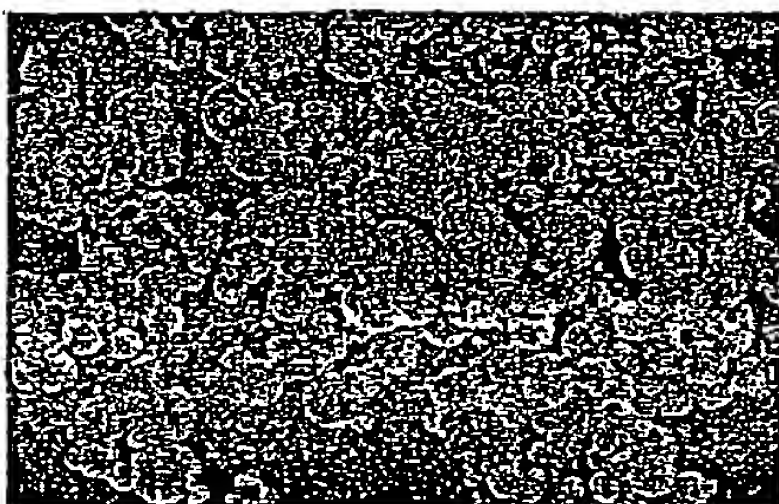


Liquid epoxy encapsulating materials

For inquiry 6

This is a liquid epoxy resin encapsulating material for the protection and adhesion of semiconductor devices.

- Features** ● Excellent low stress, adhesive, and penetration property
- Applications** ● Under filling, COB potting, hermetic seal, and other uses for electrical or mechanical protection and highly reliable adhesion of semiconductor devices



True spherical shape ultra-fine particulates "ADMAFINE"

For inquiry 19

ADMAFINE is true spherical shape ultra-fine particulates produced using a special process of oxidize metallic powder. Admatecs, a joint venture of Toyota Motor, Shin-Etsu Chemical, Shin-Etsu Quartz Products and Tatsumori, succeeded in commercial production of this product as a pioneer in the world.

- Features**
- The true spherical shape ultra-fine particulates have a sharp granular distribution, capable of improving the toughness, flowability, thermal conductivity and other physical properties of composite materials.
 - Not only simple oxide but also of composite oxide fine spherical particulates can be produced.
 - It is possible to coat the particles with various types of composites or classify the particles.
- Applications**
- Filler material for semiconductor enclosure applications
 - Filler material for precision resin molding applications
 - Anti-blocking materials
 - Sintering materials

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